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Author: Cheng Li Zhongzhu Ma Xianwei Zhang Hong Fan Jintao Wan



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Silicone-modified phenolic resin: relationships between molecular structure and curing behavior

Cheng Li ^a, Zhongzhu Ma ^a, Xianwei Zhang ^a, Hong Fan ^{a,*}, Jintao Wan ^{b,**}

^a State Key Laboratory of Chemical Engineering, College of Chemical and Biological Engineering, Zhejiang University, Hangzhou 310027, China

^b Madrid Institute for Advanced Studies of Materials (IMDEA-Materials), C/Eric Kandel, 2, Getafe (Madrid) 28906, Spain

*Hong Fan (E-mail: hfan@zju.edu.cn, Tel: 86-571-87952483, Fax: 86-571-87951612)

**Jintao Wan (E-mail: wan_jintao@yahoo.com.cn)

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